For Immediate Release:

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Circuit Technology Center Expands BGA Re-balling Capacity

September 26, 2022 - Haverhill, MA USA - Circuit Technology Center announced it recently received and commissioned a second Heller 1707-MK III in-line solder reflow oven. This new machine doubles the existing in-line reflow oven capacity to meet increasing customer demand for high-volume BGA component re-balling applications. The BGA re-balling department at Circuit Technology Center now features four robotic hot solder dip machines for the automated de-balling of BGA devices, two in-line Heller reflow ovens, two batch cleaning systems, and multiple MSL bake and dry ovens.

The company also reports that it recently purchased additional Finetech-Martin benchtop minioven systems and now has ten benchtop systems to support low to mid-volume re-balling applications. All equipment and processes comply with stringent J-STD-001, IPC 7711/7721, and IEC TS 62647-4 standards.

"For nearly 40 years, leading electronics manufacturing companies have relied on Circuit Technology Center as the world leader and innovator for circuit board modification, rework and damage repair services," said Andy Price, Sales Manager. "We are thrilled to announce these new equipment purchases and capacity expansion, offering our customers the most advanced BGA component re-balling department in the industry with the capacity, flexibility, and expertise to support high and low volume requirements."

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Circuit Technology Center, founded in 1979, continues to be recognized as the most innovative and reliable specialist in circuit board damage repair, rework, BGA re-balling and component level modification services in the world.

For more information, please visit: www.circuitrework.com. Phone: 978-374-5000, Fax: 978-372-5700, Web: www.circuitrework.com.